

L Number	Hits	Search Text	DB	Time stamp
-	163	(IC adj package).ti.	USPAT; US-PGPUB	2003/08/13 15:59
-	216	(IC adj package).ti.	USPAT; US-PGPUB	2003/03/22 11:05
-	16	((IC adj package).ti.) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:15
-	2	((((IC adj package).ti.) and 439/\$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	1	((((IC adj package).ti.) and 324/\$.ccls.) and bond	USPAT; US-PGPUB	2003/03/22 11:14
-	432	324/\$.ccls. and package and adhesive and chip	USPAT; US-PGPUB	2003/03/22 11:15
-	280	324/\$.ccls. and package and adhesive and chip and bond	USPAT; US-PGPUB	2003/03/22 11:15
-	19	324/\$.ccls. and package and adhesive and chip and bond and indium	USPAT; US-PGPUB	2003/03/22 12:42
-	36	((IC adj package).ti.) and 439/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:49
-	5166	(package near comprising).clm.	USPAT; US-PGPUB	2003/03/22 11:50
-	0	((package near comprising).clm.) and conductive near2 adheshiv	USPAT; US-PGPUB	2003/03/22 11:53
-	1	((package near comprising).clm.) and ECA	USPAT; US-PGPUB	2003/03/22 11:51
-	55	((package near comprising).clm.) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:52
-	0	((((package near comprising).clm.) and 324/\$.ccls.) and adheshiv	USPAT; US-PGPUB	2003/03/22 11:52
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 11:52
-	17	((package near comprising).clm.) and 324/\$.ccls.) and adhesive	USPAT; US-PGPUB	2003/03/22 11:53
-	194	((package near comprising).clm.) and conductive near2 adhesive	USPAT; US-PGPUB	2003/03/22 12:24
-	3	((package near comprising).clm.) and conductive near2 adhesive) and 324/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:57
-	104	((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.	USPAT; US-PGPUB	2003/03/22 11:58
-	94	((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and bond\$	USPAT; US-PGPUB	2003/03/22 12:00
-	62	((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$	USPAT; US-PGPUB	2003/03/22 12:03
-	41	(((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$) and (gold indium)	USPAT; US-PGPUB	2003/03/22 12:22
-	2	(((((package near comprising).clm.) and conductive near2 adhesive) and 257/\$.ccls.) and wire adj bond\$) and indium	USPAT; US-PGPUB	2003/03/22 12:22
-	3	((package near comprising).clm.) and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:24
-	3	324/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	439/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	23	257/\$.ccls. and package and adhesive with indium	USPAT; US-PGPUB	2003/03/22 12:55
-	2	"6489178"	USPAT; US-PGPUB	2003/03/22 13:29
-	2	("5151276"   "5897338").PN.	USPAT	2003/03/22 13:29
-	1059	438/118-119.ccls.	USPAT; US-PGPUB	2003/03/22 13:51

-	66	438/118-119.ccls. and indium	USPAT;	2003/03/22
-	2	438/118-119.ccls. and adhesive with indium	US-PGPUB	13:44
-	1136	438/106.ccls.	USPAT;	2003/03/22
-	2	438/106.ccls. and adhesive with indium	US-PGPUB	13:44
-	1394	438/14-15.ccls.	USPAT;	2003/03/22
-	227	438/14-15.ccls. and adhesive	US-PGPUB	13:53
-	1	438/14-15.ccls. and adhesive with indium	USPAT;	2003/03/22
-	530	438/15.ccls.	US-PGPUB	13:52
-	224	438/15.ccls. and therm\$	USPAT;	2003/03/22
-	0	(438/15.ccls. and therm\$) and induim	US-PGPUB	13:57
-	16	(438/15.ccls. and therm\$) and indium	USPAT;	2003/03/22
-	2	((("6251696") or ("5994716"))).PN.	US-PGPUB	13:54
-	390	eutectic with indium	USPAT;	2003/03/22
-	6	(eutectic with indium) and 324/\$.ccls.	US-PGPUB	13:54
-	574	aluminum with boron with beryllium with oxide	USPAT;	2003/03/22
-	766	aluminum with boron with beryllium with oxide	US-PGPUB	13:58
-	192	aluminum with boron with beryllium with oxide with ceramic	USPAT;	2003/03/22
-	0	(aluminum with boron with beryllium with oxide with ceramic) and 324/\$.ccls.	US-PGPUB	13:57
-	23	aluminum with boron with beryllium with oxide with ceramic with substrate	USPAT;	2003/03/22
-	31	semiconductor near2 thermal near2 sensor	US-PGPUB	14:10
-	0	(semiconductor near2 thermal near2 sensor) and washer	USPAT;	2003/03/22
-	11	(semiconductor near2 thermal near2 sensor) and mount	US-PGPUB	14:10
-	0	(semiconductor near2 thermal near2 sensor) and mount	USPAT;	2003/03/22
-	20	semiconductor near2 thermal near2 sensor	US-PGPUB	15:20
-	2	((("6251696") or ("5126813"))).PN.	USPAT;	2003/03/22
-	1	((("6251696") or ("5126813"))).PN.) and size	US-PGPUB	15:24
-	1	((("6251696") or ("5126813"))).PN.) and mm	USPAT;	2003/03/22
-	688	438/17.ccls.	US-PGPUB	15:25
-	3	438/17.ccls. and bonding adj condition	USPAT;	2003/03/22
-	0	438/17.ccls. and thermoelectroc	US-PGPUB	15:26
-	2	438/17.ccls. and thermoelectric	USPAT;	2003/03/22
-	4	thermoelectric adj analyzer	US-PGPUB	15:26
-	0	6570390.URPN.	USPAT;	2003/03/22
-	4	("4912052"   "5097204"   "5393980"   "5543334").PN.	EPO; JPO; DERWENT; IBM_TDB	2003/03/22
			EPO; JPO; DERWENT; IBM_TDB	16:44
			USPAT;	2003/03/22
			US-PGPUB	17:27
			USPAT;	2003/03/22
			US-PGPUB	17:28
			USPAT;	2003/03/22
			US-PGPUB	17:28
			USPAT;	2003/08/13
			US-PGPUB	16:20
			USPAT;	2003/08/13
			US-PGPUB	16:02
			USPAT;	2003/08/13
			US-PGPUB	16:20
			USPAT;	2003/08/13
			US-PGPUB	16:22
			USPAT;	2004/02/20
			US-PGPUB	15:02
			USPAT	2003/08/13
				16:24
			USPAT	2003/08/13
				16:24

-	7	thermoelectric near2 analyzer	USPAT;	2004/02/20
-	1	"6570390"	US-PGPUB	15:54
-	4	("4912052"   "5097204"   "5393980"   "5543334").PN.	USPAT;	2004/02/20
-	5	indium near gold\$ltin near alloy	US-PGPUB	15:02
-	251	324/\$.ccls. and thermoelectric	USPAT	2004/02/20
-	61	(324/\$.ccls. and thermoelectric) and (indium gold)	15:03	
-	9758	hirayama.in.	USPAT;	2004/02/20
-	22	hirayama.in. and (thermo\$electric thermocouple)	US-PGPUB	16:43
-	1	2003-203080.NRAN.	USPAT;	2004/02/20
-	16	324/451.ccls. and (thermo\$electric thermocouple)	US-PGPUB	16:44
-	4	324/451.ccls. and (thermo\$electric thermocouple) and (indium gold)	USPAT;	2004/02/20
-	301	374/\$.ccls. and (thermo\$electric thermocouple) and (indium gold)	US-PGPUB	17:44
-	114	374/\$.ccls. and thermo\$electric and (indium gold)	EPO; JPO;	2004/02/20
-	17	374/\$.ccls. and thermo\$electric and (indium gold) and adhesive	DERWENT;	17:44
			IBM_TDB	
			EPO; JPO;	2004/02/20
			DERWENT;	17:50
			IBM_TDB	
			DERWENT	2004/02/20
				17:48
			USPAT;	2004/02/20
			US-PGPUB	17:53
			USPAT;	2004/02/20
			US-PGPUB	17:57
			USPAT;	2004/02/20
			US-PGPUB	17:58
			USPAT;	2004/02/20
			US-PGPUB	17:59
			USPAT;	2004/02/20
			US-PGPUB	17:59